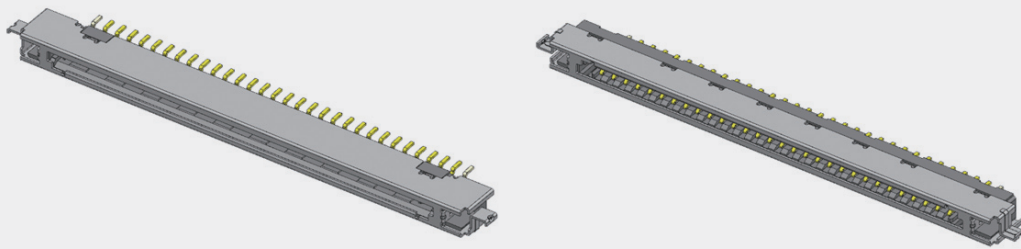


FPC/FFC Connectors (Display)

Power up Reverse

Applications | Mobile device, Display, PC



- ▶ 0.5mm pitch, 2.30mm(Max.) height, Reverse type connector
- ▶ Widely used in a variety of markets including PC, TV etc.
- ▶ Ease mating, 30 cycle durability
- ▶ High data rate transfer
- ▶ Anti-reverse mating design

Code & Specification

Mating Size / Unit : (mm)

| Product Code | Pitch (mm) | No. of Contacts | Width (mm) | Height (mm) | Length | Remark |
|----------------|------------|-----------------|------------|-------------|--------|--------|
| IS100-L30R-C23 | 1.00 | 30 | 5.35 | 2.30 | 40.05 | - |

| Rated Current | Contact Resistance | Withstanding voltage | Temperature Range |
|---|--------------------|----------------------|-------------------|
| 1.0A/Pin (Applicable Wire : AWG #30) | 40mΩ (Max.) | 500V AC(RMS) | -35°C ~ 85°C |

FPC/FFC Connectors (Display)

Power up Reverse

Applications | Mobile device, Display, PC

Product Specification

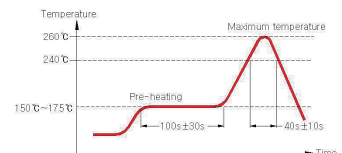
| | | | | | | |
|---------|---------------|-----------------|-----------------------------|----------------|---------------------------|-----------------------------|
| Ratings | Rated current | 1.0A/Pin | Operating temperature range | -35°C to +85°C | Storage temperature range | 15°C to 35°C (With packing) |
| | Rated voltage | 200V AC(RMS)/DC | Operating humidity range | 70%RH Max. 2 | Storage humidity range | 65%RH Max. 2 |

- 1) Including terminal temperature rise.
- 2) Storage area is to be free of corrosive gases and dew formation.

| Items | Specifications | Conditions |
|--------------------------|---|---|
| 1. Contact resistance | 40mΩ [Max.] | - Open circuit voltage: 20mV Max.(AC) - Test current: 10mA. |
| 2. Insulation resistance | 100MΩ [Min.] | 100V DC |
| 3. Withstanding voltage | No flashover or dielectric breakdown | 500V AC(RMS) for 1minute |
| 4. Insertion Force | 6.0kgf [Max.] | Measured force to insert wafer assembly into the housing assembly which has same circuits. (Speed 25mm/Min) |
| 5. Withdrawal Force | 0.75kgf [Min] | Measured forces to withdraw wafer assembly from the housing assembly which has same circuits. (Speed 25mm/Min) |
| 6. Durability | Contact resistance - 80mΩ [Max.] | Measured after 30 cycle total insertion and withdrawal operation. |
| 7. Vibration | 1) Contact resistance - 80mΩ [Max.] 2) No damage, loose part no crack | - Vibration frequency range : 10~55Hz - Total amplitude : 1.5mm - Sweep ration : 10-55-10Hz/Min - Duration : 2h each (6h in total) |
| 8. Humidity | 1) Contact resistance - 80mΩ [Max.] 2) Insulation resistance : 50MΩ [Min.] | - Temperature : 40°C±2°C - Relative humidity : 90% RH to 95% RH - Duration : 96hr |

9. Solder heat resistance No loose contacts no deformation.

Reflow condition. (Refer to Reflow)



Materials / Finish

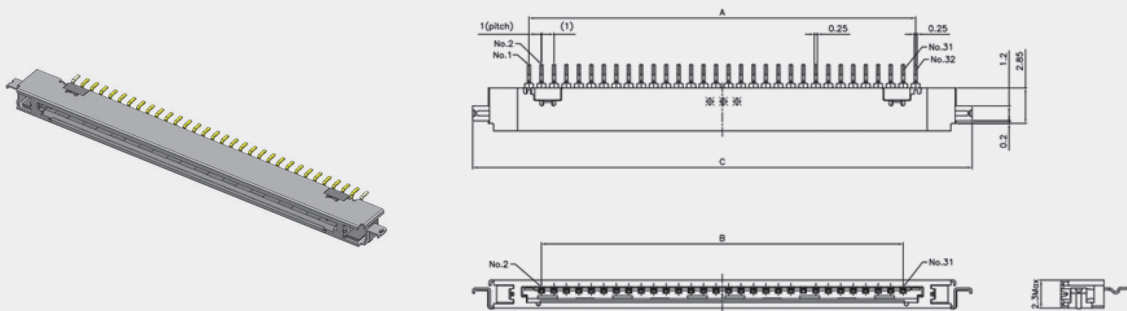
| Part | Materials | Finish | UL Regulation |
|------------------|-----------------|----------------|---------------|
| Base | LCP | Black | UL94V-0 |
| Contact Terminal | Phosphor Bronze | Au , Ni plated | - |
| Cover | Stainless Steel | Pre-plating Sn | - |

FPC/FFC Connectors (Display)

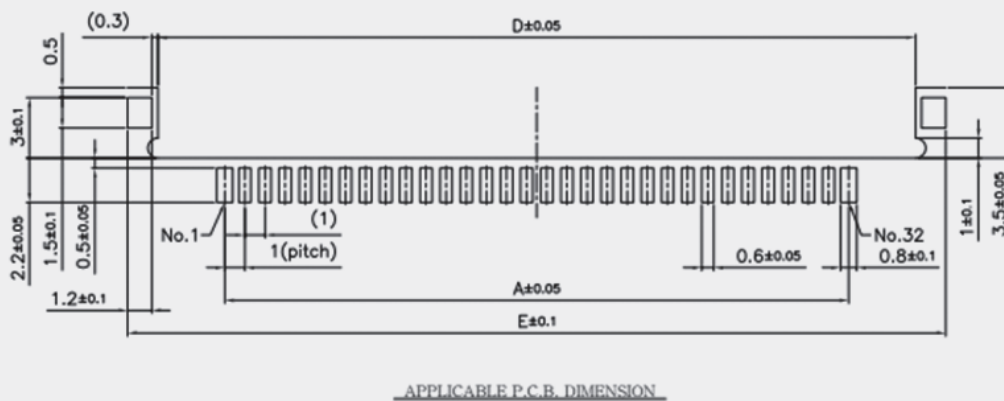
Power up Reverse

Applications | Mobile device, Display, PC

Product Drawing



Recommended PCB, Metal Mask Layout



Mating Size / Unit : (mm)

| Product No. | No. of Contacts | A | B | C | D | E |
|----------------|-----------------|-------|-------|-------|-------|-------|
| IS100-L30R-C23 | 30 | 31.00 | 29.00 | 40.05 | 37.65 | 40.65 |